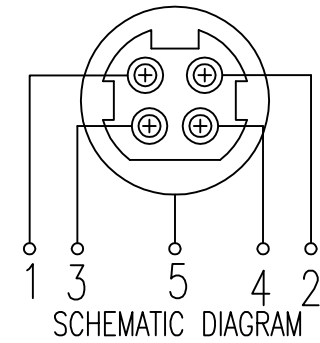
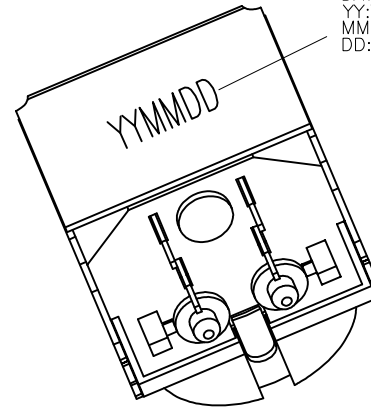
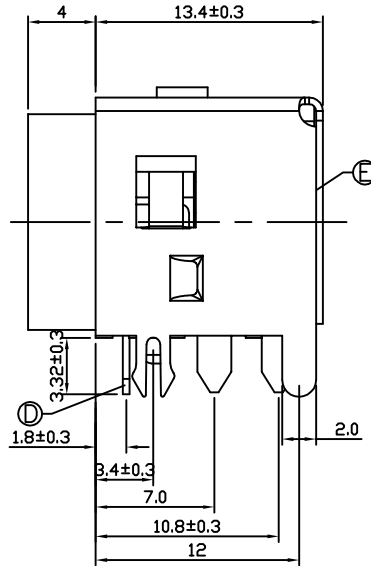
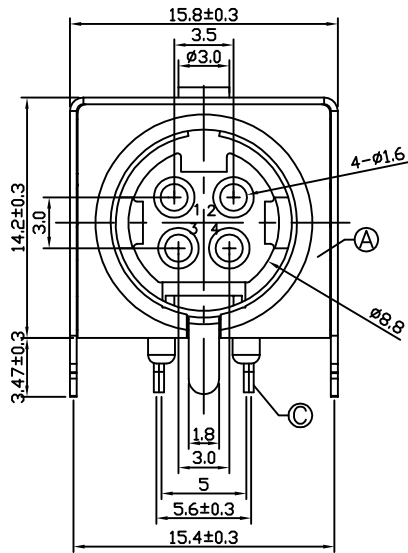


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR RELEASE	IVY-C	2017.02.24

DATE CODE
YY:YEAR
MM:MONTH
DD:DATE



SPECIFICATIONS:

1. TO CONFORM TO THE SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
2. HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
3. PACKAGE: SEE "2MJ1513-000111F" PACKAGE.
4. FOR WAVE SOLDERING LEAD-FREE PROCESS.
5. OTHER GENERAL SPEC. TO REFER "2MJ1513-000111F SPEC"

PART NO.
2MJ1513-000111F

CONTACT PLATING

1. Ag

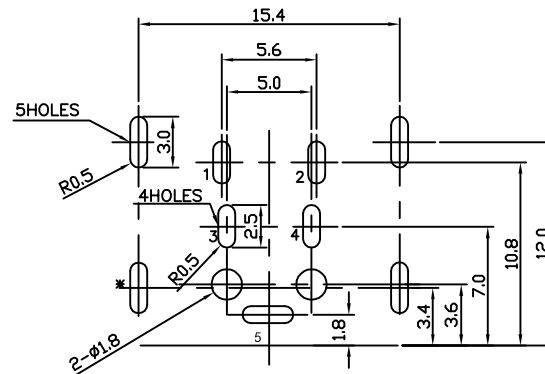
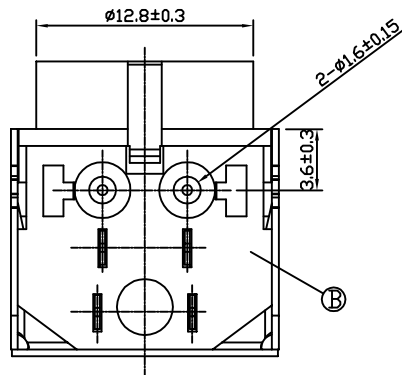
SUFFIX: HALOGEN FREE

PACKAGE

1: Tray

HOUSING COLOR

1: BLACK



T:1.6 Dimensions of PC board holes
Tolerance : ±0.05(Printed-Top view)

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
E	SHELL	1	SPCC	CuSn Plating
D	GROUND CONTACT	1	BRASS	CuSn Plating
C	TERMINAL	4	BRASS	Ag Plating
B	COVER	1	PBT UL 94V-0	BLACK
A	HOUSING	1	PBT UL 94V-0	BLACK

UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司	
DECIMALS:	ANGLES:	TITLE	MINI DIN CONNECTOR
X : ±0.5	X : ±2°	DWN	NY-C 2017.02.24 PART NO.2MJ1513-000111F
X.X : ±0.3	X.X : ±1°	CHKD	ANGELA2017.02.24 SCALE 1:1 UNIT: mm
X.XX : ±0.2		APVD	ANGELA2017.02.24 SIZE: A3 SHEET:1 OF 1 REV: A
CUSTOMER COPY			